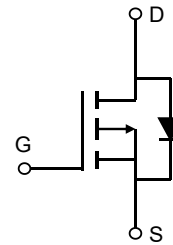


### Description

#### Features

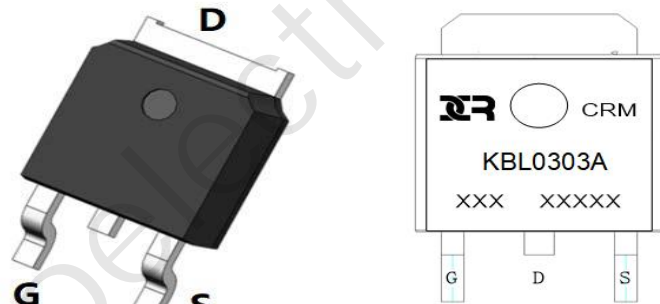
- -30V, -100A  
 $R_{DS(ON)}$  Typ = 3.6mΩ @  $V_{GS} = -10V$   
 $R_{DS(ON)}$  Typ = 6mΩ @  $V_{GS} = -4.5V$
- Advanced Trench Technology
- Excellent  $R_{DS(ON)}$  and Low Gate Charge
- 100% UIS TESTED!
- 100%  $\Delta V_{ds}$  TESTED!



Schematic Diagram

#### Application

- Load Switch
- PWM Application
- Power Management



Marking and Pin Assignment

#### Package Marking and Ordering Information

Device	Marking	Package	Outline	Reel Size	Reel (pcs)	Per Carton (pcs)
CRMKBL0303A	CRMKBL0303A	TO-252-3L	TAPING	13"	2500	25000

#### Absolute Maximum Ratings (@ $T_J = 25^\circ\text{C}$ unless otherwise specified)

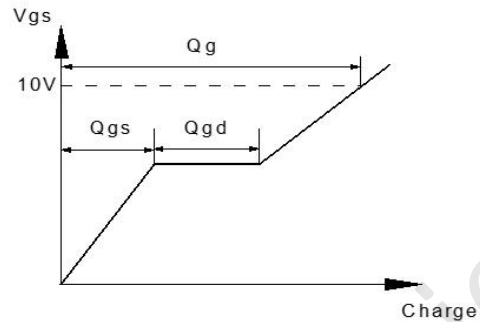
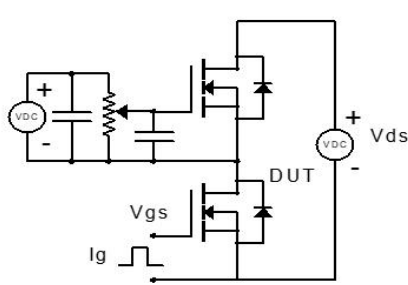
Symbol	Parameter	Value	Units
$V_{DS}$	Drain-to-Source Voltage	-30	V
$V_{GS}$	Gate-to-Source Voltage	$\pm 20$	V
$I_D$	Continuous Drain Current	$T_C = 25^\circ\text{C}$	-100
		$T_C = 100^\circ\text{C}$	-60
$I_{DM}$	Pulsed Drain Current <sup>(1)</sup>	-400	A
$E_{AS}$	Single Pulsed Avalanche Energy <sup>(2)</sup>	248	mJ
$P_D$	Power Dissipation	$T_C = 25^\circ\text{C}$	78
$R_{\theta JC}$	Thermal Resistance, Junction to Case	1.6	$^\circ\text{C/W}$
$T_J, T_{STG}$	Junction & Storage Temperature Range	-55 to 150	$^\circ\text{C}$

### Electrical Characteristics (T<sub>J</sub> = 25°C unless otherwise specified)

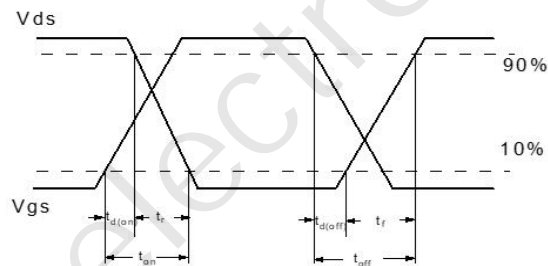
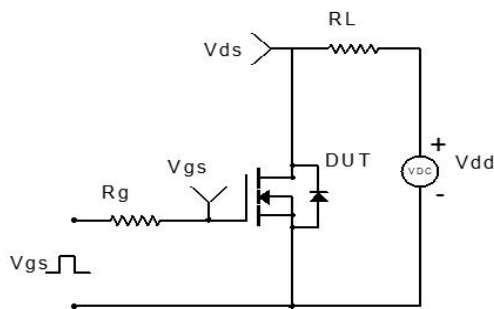
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
<b>Off Characteristics</b>						
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	I <sub>D</sub> = -250μA, V <sub>GS</sub> = 0V	-30	-	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = -30V, V <sub>GS</sub> = 0V	-	-	-1.0	μA
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>DS</sub> = 0V, V <sub>GS</sub> = ±20V	-	-	±100	nA
<b>On Characteristics</b>						
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = -250μA	-1.2	-1.6	-2.2	V
R <sub>DS(ON)</sub>	Static Drain-Source ON-Resistance <sup>(3)</sup>	V <sub>GS</sub> = -10V, I <sub>D</sub> = -20A	-	3.6	4.7	mΩ
		V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -10A	-	6	7.8	mΩ
<b>Dynamic Characteristics</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> = 0V, V <sub>DS</sub> = -15V, f = 1MHz	-	3910	-	pF
C <sub>oss</sub>	Output Capacitance		-	692	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		-	561	-	pF
Q <sub>g</sub>	Total Gate Charge	V <sub>GS</sub> = 0 to -10V V <sub>DS</sub> = -15V, I <sub>D</sub> = -30A	-	78	-	nC
Q <sub>gs</sub>	Gate Source Charge		-	13	-	nC
Q <sub>gd</sub>	Gate Drain("Miller") Charge		-	18	-	nC
<b>Switching Characteristics</b>						
t <sub>d(on)</sub>	Turn-On DelayTime	V <sub>GS</sub> = -10V, V <sub>DD</sub> = -15V I <sub>D</sub> = -30A, R <sub>GEN</sub> = 3Ω	-	17.5	-	ns
t <sub>r</sub>	Turn-On Rise Time		-	50	-	ns
t <sub>d(off)</sub>	Turn-Off DelayTime		-	108	-	ns
t <sub>f</sub>	Turn-Off Fall Time		-	70	-	ns
<b>Drain-Source Diode Characteristics and Max Ratings</b>						
I <sub>S</sub>	Maximum Continuous Drain to Source Diode Forward Current		-	-	-100	A
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current		-	-	-400	A
V <sub>SD</sub>	Drain to Source Diode Forward Voltage	V <sub>GS</sub> = 0V, I <sub>S</sub> = -20A	-	-	-1.2	V
trr	Body Diode Reverse Recovery Time	I <sub>F</sub> = -30A, di/dt = 100A/us	-	33	-	ns
Qrr	Body Diode Reverse Recovery Charge		-	40	-	nC

- Notes:
1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
  2. E<sub>AS</sub> condition: Starting T<sub>J</sub>=25°C, V<sub>DD</sub>=-15V, V<sub>G</sub>=-10V, R<sub>G</sub>=25ohm, L=0.5mH, I<sub>AS</sub>=-31.5A
  3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 0.5%.

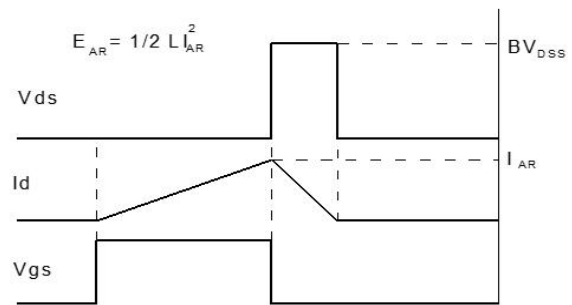
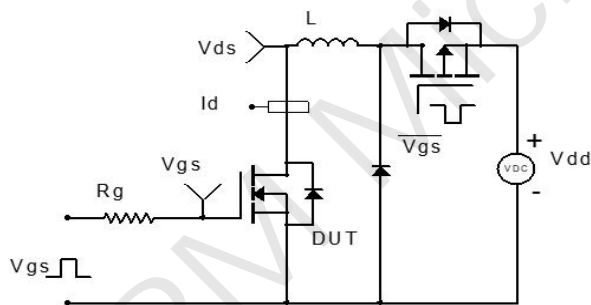
**Test Circuit**



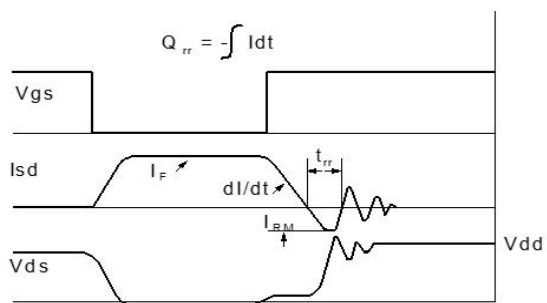
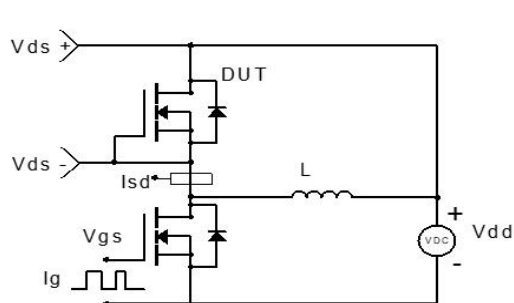
**Figure 1: Gate Charge Test Circuit & Waveform**



**Figure 2: Resistive Switching Test Circuit & Waveform**

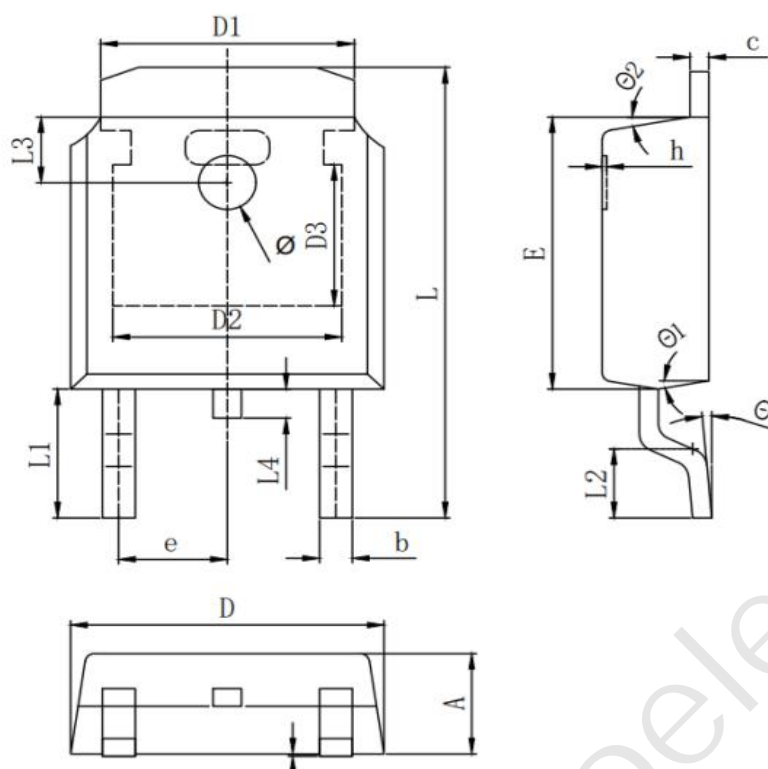


**Figure 3: Unclamped Inductive Switching Test Circuit & Waveform**



**Figure 4: Diode Recovery Test Circuit & Waveform**

### Package Mechanical Data(TO-252-3L)




SYMBOL	MILLIMETER		
	MIN	Typ.	MAX
A	2.200	2.300	2.400
A1	0.000		0.127
b	0.640	0.690	0.740
c (电镀后)	0.460	0.520	0.580
D	6.500	6.600	6.700
D1	5.334 REF		
D2	4.826 REF		
D3	3.166 REF		
E	6.000	6.100	6.200
e	2.286 TYP		
h	0.000	0.100	0.200
L	9.900	10.100	10.300
L1	2.888 REF		
L2	1.400	1.550	1.700
L3	1.600 REF		
L4	0.600	0.800	1.000
Φ	1.100	1.200	1.300
θ	0°		8°
θ 1	9° TYP		
θ 2	9° TYP		

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